

**STS2NF100****N-CHANNEL 100V - 0.23 Ω - 6A SO-8
STripFET™ II POWER MOSFET**

| TYPE | V _{DSS} | R _{D(on)} | I _D |
|-----------|------------------|--------------------|----------------|
| STS2NF100 | 100 V | <0.26 Ω | 6 A |

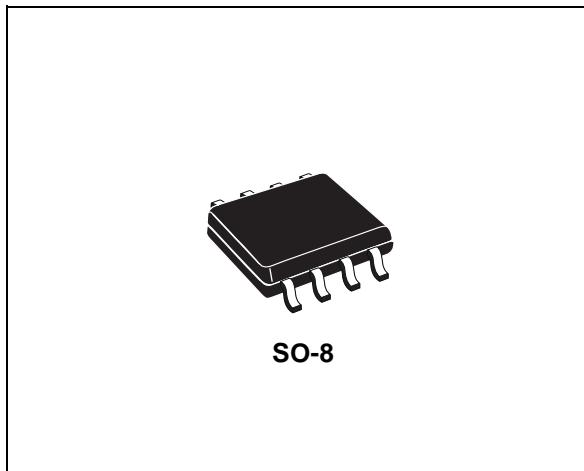
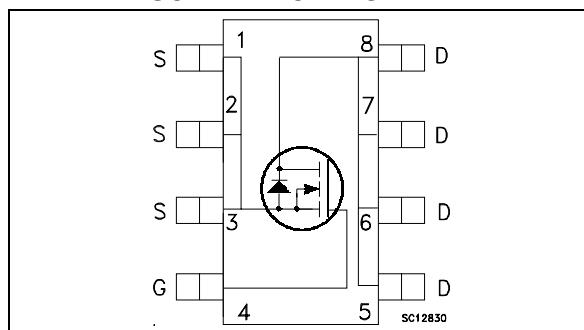
- TYPICAL R_{D(on)} = 0.23 Ω
- EXCEPTIONAL dv/dt CAPABILITY
- 100 % AVALANCHE TESTED
- APPLICATION ORIENTED CHARACTERIZATION

DESCRIPTION

This MOSFET series realized with STMicroelectronics unique STripFET process has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced high-efficiency, high-frequency isolated DC-DC converters for Telecom and Computer applications. It is also intended for any applications with low gate drive requirements.

APPLICATIONS

- HIGH-EFFICIENCY DC-DC CONVERTERS
- UPS AND MOTOR CONTROL

**INTERNAL SCHEMATIC DIAGRAM****ABSOLUTE MAXIMUM RATINGS**

| Symbol | Parameter | Value | Unit |
|---------------------|--|------------|------|
| V _{DS} | Drain-source Voltage (V _{GS} = 0) | 100 | V |
| V _{DGR} | Drain-gate Voltage (R _{GS} = 20 kΩ) | 100 | V |
| V _{GS} | Gate-source Voltage | ± 20 | V |
| I _{D(•)} | Drain Current (continuous) at T _C = 25°C | 2 | A |
| I _D | Drain Current (continuous) at T _C = 100°C | 1.3 | A |
| I _{DM(••)} | Drain Current (pulsed) | 8 | A |
| P _{tot} | Total Dissipation at T _C = 25°C | 2.5 | W |
| | Derating Factor | 0.016 | W/°C |
| dV/dt (1) | Peak Diode Recovery voltage slope | 40 | V/ns |
| E _{AS} (2) | Single Pulse Avalanche Energy | 200 | mJ |
| T _{stg} | Storage Temperature | -65 to 175 | °C |
| T _j | Max. Operating Junction Temperature | | |

(••) Pulse width limited by safe operating area.

(•) Current limited by the package

(1) I_{SD} ≤ 2A, di/dt ≤ 300A/μs, V_{DD} ≤ V_{(BR)DSS}, T_j ≤ T_{JMAX}(2) Starting T_j = 25 °C, I_D = 3A, V_{DD} = 50V

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THERMAL DATA

| | | | |
|--|--|--------------------------------|------------------|
| R _{thj-amb} T _j T _{stg} | (*) Thermal Resistance Junction-ambient Thermal Operating Junction-ambient Storage Temperature | 50 -55 to 150 -55 to 150 | °C/W °C °C |
|--|--|--------------------------------|------------------|

(*) Mounted on FR-4 board ($t \leq 10$ sec.)

ELECTRICAL CHARACTERISTICS ($T_{case} = 25$ °C unless otherwise specified)

OFF

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|----------------------|---|---|------|------|---------|----------|
| V _{(BR)DSS} | Drain-source Breakdown Voltage | I _D = 250 μA, V _{GS} = 0 | 100 | | | V |
| I _{DSS} | Zero Gate Voltage Drain Current (V _{GS} = 0) | V _{DS} = Max Rating V _{DS} = Max Rating T _C = 125°C | | | 1 10 | μA μA |
| I _{GSS} | Gate-body Leakage Current (V _{DS} = 0) | V _{GS} = ± 20 V | | | ±100 | nA |

ON (*)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------------|-----------------------------------|---|------|------|------|------|
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} I _D = 250 μA | 2 | 3 | 4 | V |
| R _{DS(on)} | Static Drain-source On Resistance | V _{GS} = 10 V I _D = 1 A | | 0.23 | 0.26 | Ω |

DYNAMIC

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|--|---|--|------|-----------------|------|----------------|
| g _{fs} (*) | Forward Transconductance | V _{DS} >I _{D(on)} ×R _{DS(on)max} I _D = 1 A | | 0.5 | | S |
| C _{iss} C _{oss} C _{rss} | Input Capacitance Output Capacitance Reverse Transfer Capacitance | V _{DS} = 25V, f = 1 MHz, V _{GS} = 0 | | 280 45 20 | | pF pF pF |

ELECTRICAL CHARACTERISTICS (continued)**SWITCHING ON**

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------|--|---|------|----------------|------|----------------|
| $t_{d(on)}$ t_r | Turn-on Delay Time Rise Time | $V_{DD} = 50 \text{ V}$ $I_D = 1 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GS} = 10 \text{ V}$ (Resistive Load, Figure 3) | | 6 10 | | ns ns |
| Q_g Q_{gs} Q_{gd} | Total Gate Charge Gate-Source Charge Gate-Drain Charge | $V_{DD} = 80 \text{ V}$ $I_D = 1 \text{ A}$ $V_{GS} = 10 \text{ V}$ | | 10 2.5 4 | | nC nC nC |

SWITCHING OFF

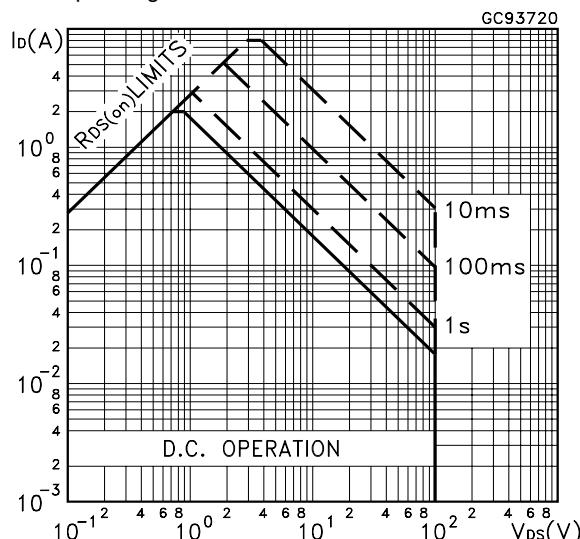
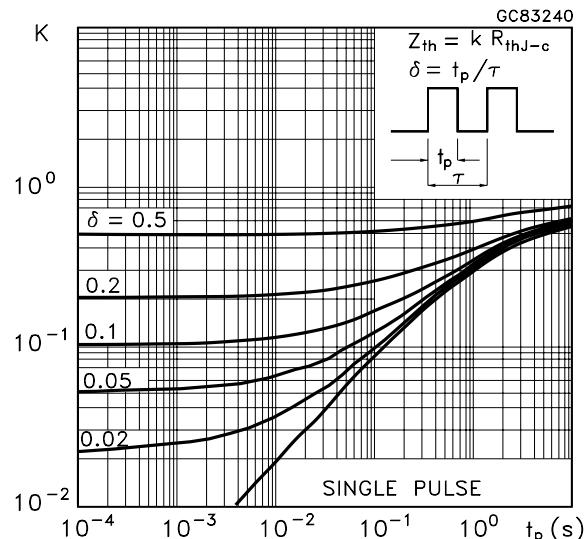
| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|------------------------------------|---|--|------|---------------|------|----------------|
| $t_{d(off)}$ t_f | Turn-off Delay Time Fall Time | $V_{DD} = 50 \text{ V}$ $I_D = 1 \text{ A}$ $R_G = 4.7 \Omega$, $V_{GS} = 10 \text{ V}$ (Resistive Load, Figure 3) | | 20 3 | | ns ns |
| $t_{r(V_{off})}$ t_f t_c | Off-Voltage Rise Time Fall Time Cross-over Time | $V_{clamp} = 80 \text{ V}$ $I_D = 1 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GS} = 10 \text{ V}$ (Inductive Load, Figure 5) | | 19 8 15 | | ns ns ns |

SOURCE DRAIN DIODE

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|-----------------------------------|--|---|------|----------------|---------|---------------|
| I_{SD} $I_{SDM} (\bullet)$ | Source-drain Current Source-drain Current (pulsed) | | | | 6 24 | A A |
| $V_{SD} (*)$ | Forward On Voltage | $I_{SD} = 2 \text{ A}$ $V_{GS} = 0$ | | | 1.3 | V |
| t_{rr} Q_{rr} I_{RRM} | Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current | $I_{SD} = 2 \text{ A}$ $di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 10 \text{ V}$ $T_j = 150^\circ\text{C}$ (see test circuit, Figure 5) | | 70 175 5 | | ns nC A |

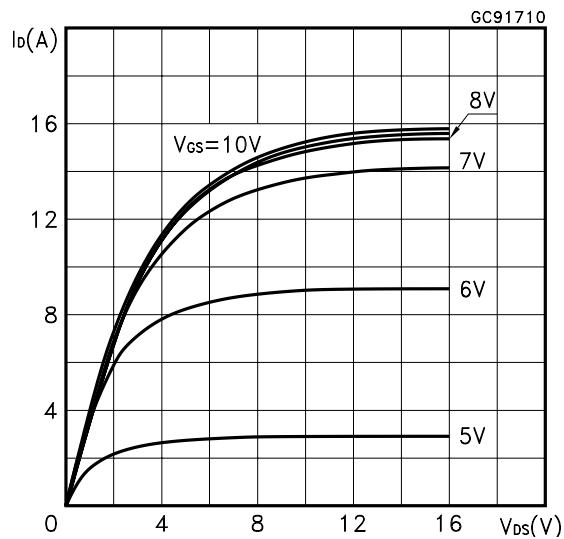
(*)Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %.

(\bullet)Pulse width limited by safe operating area.

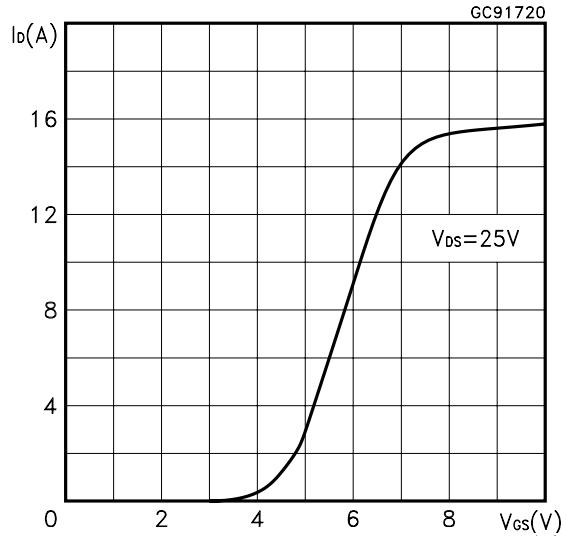
Safe Operating Area**Thermal Impedance**

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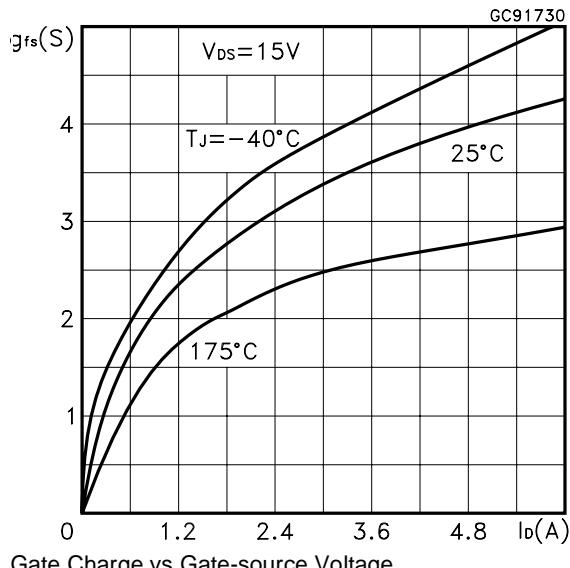
Output Characteristics



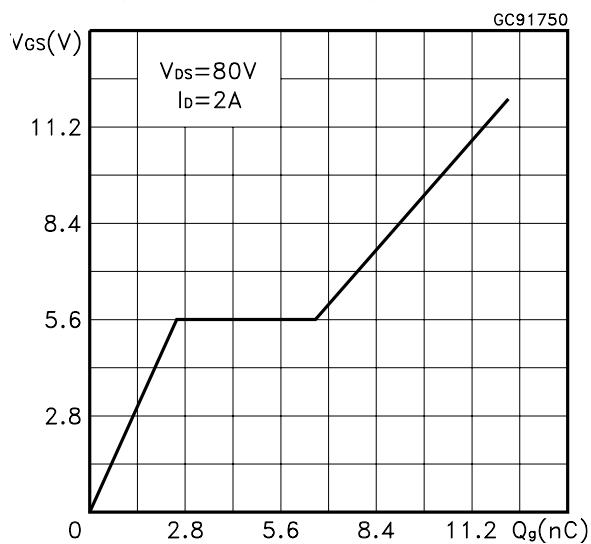
Transfer Characteristics



Transconductance

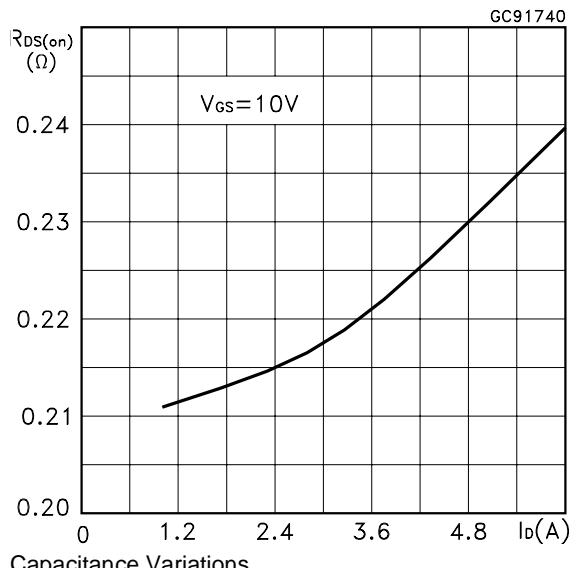


Gate Charge vs Gate-source Voltage

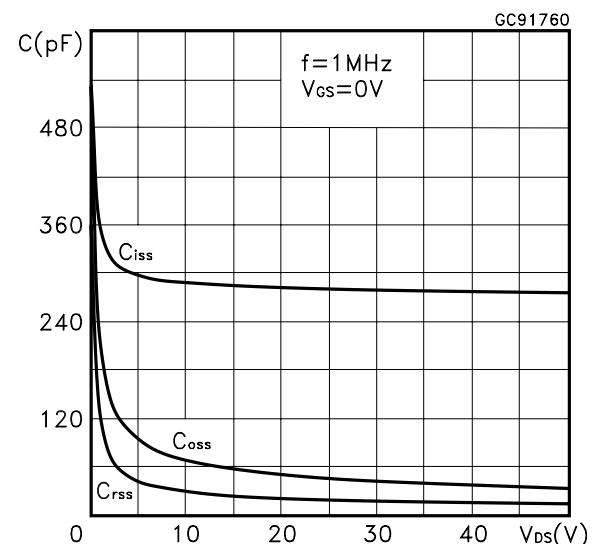


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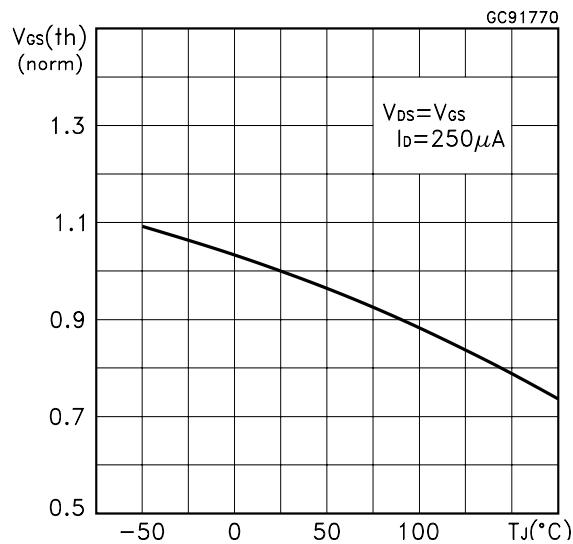
Static Drain-source On Resistance



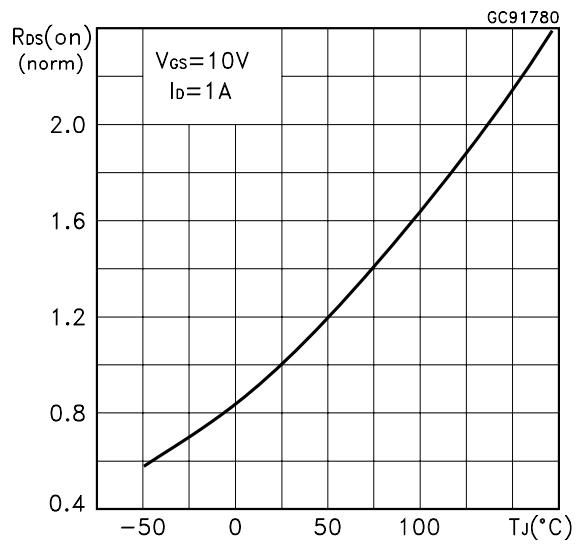
Capacitance Variations



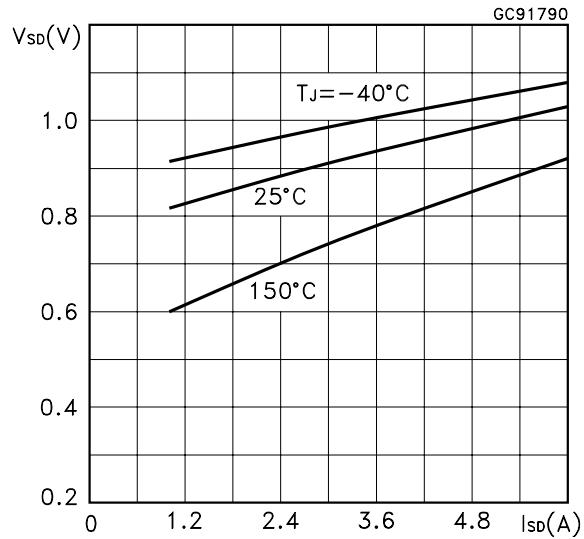
Normalized Gate Threshold Voltage vs Temperature



Normalized on Resistance vs Temperature



Source-drain Diode Forward Characteristics



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Fig. 1: Unclamped Inductive Load Test Circuit

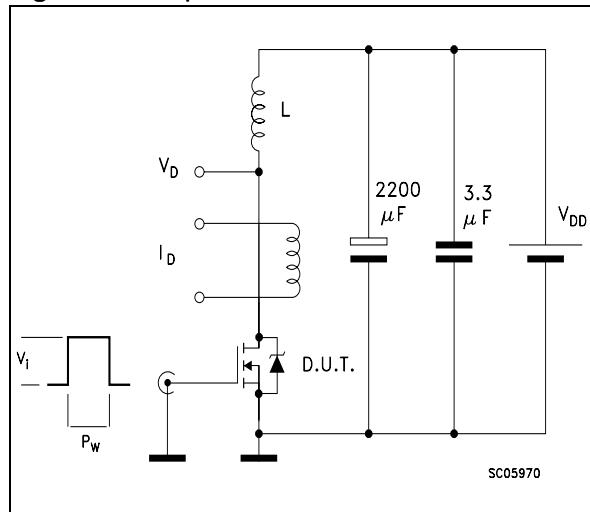


Fig. 2: Unclamped Inductive Waveform

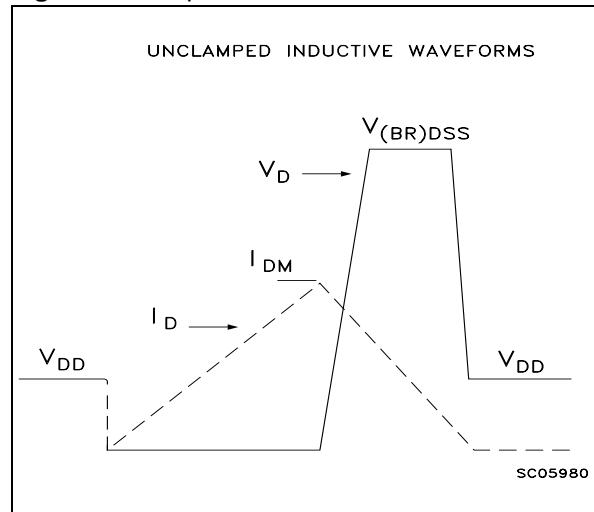


Fig. 3: Switching Times Test Circuits For Resistive Load

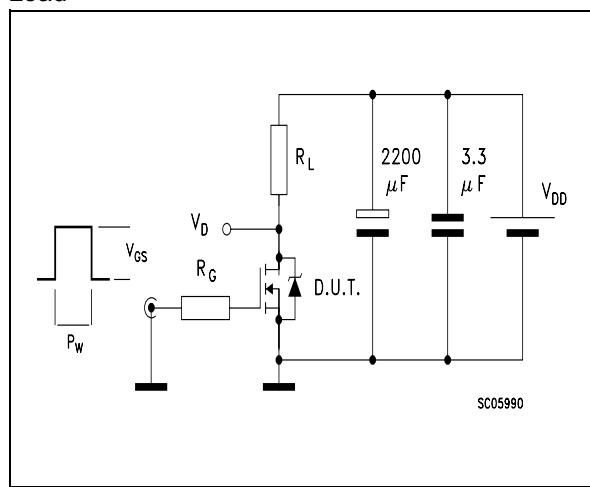


Fig. 4: Gate Charge test Circuit

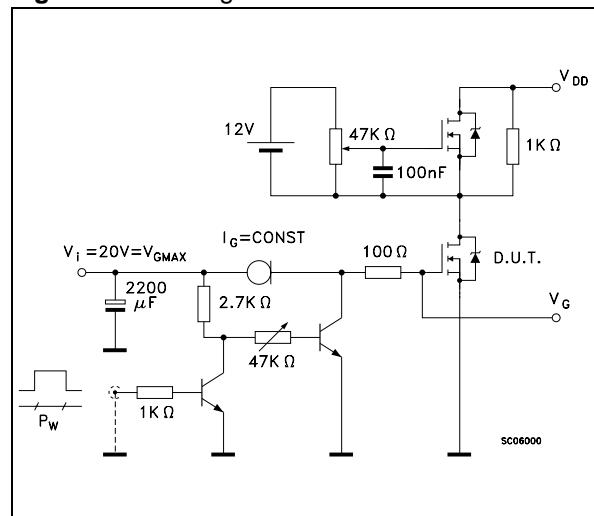
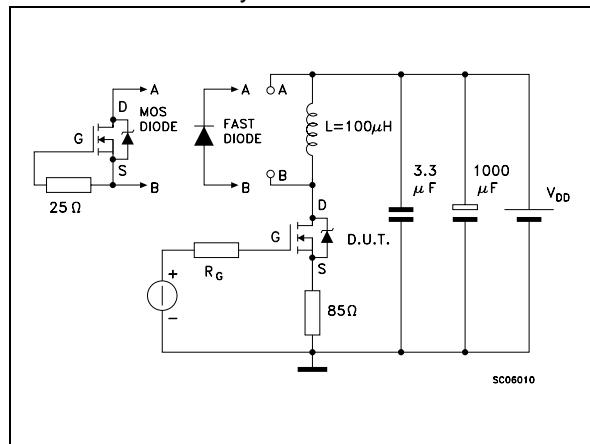
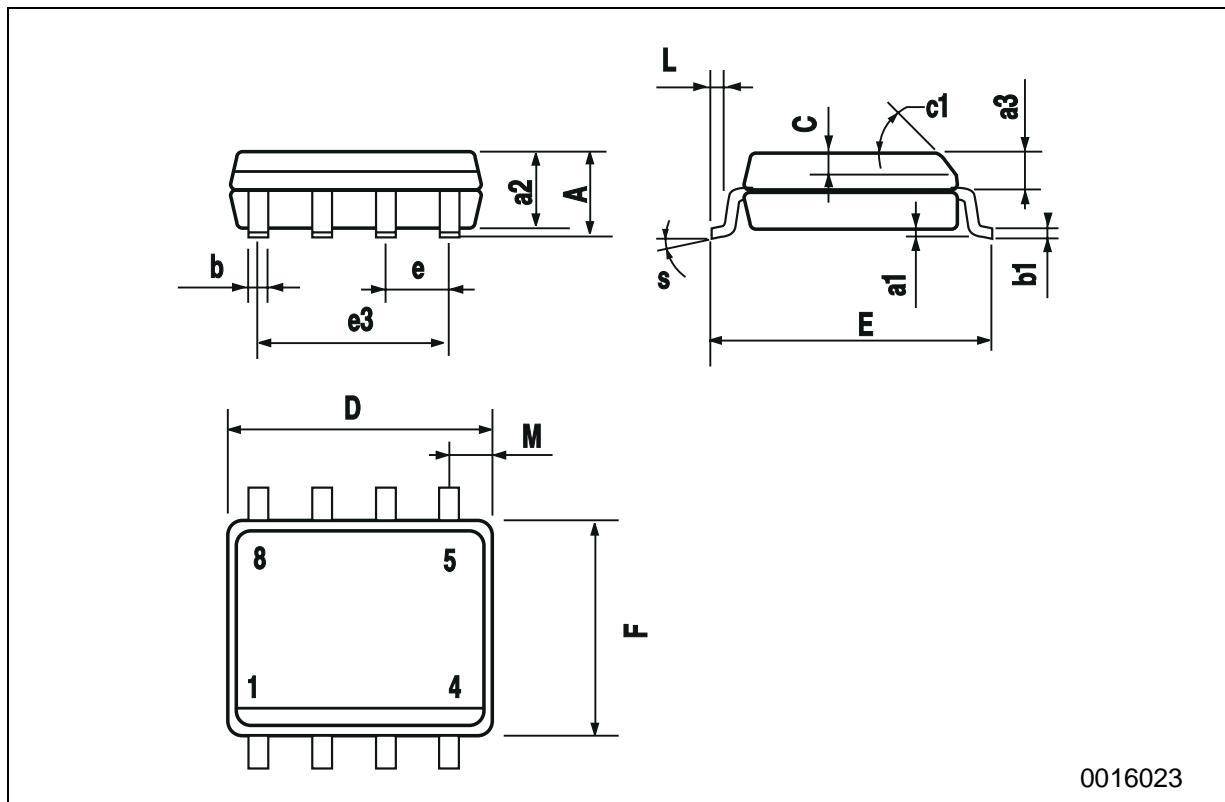


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times



SO-8 MECHANICAL DATA

| DIM. | mm | | | inch | | |
|------|------|-----------|------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | | | 1.75 | | | 0.068 |
| a1 | 0.1 | | 0.25 | 0.003 | | 0.009 |
| a2 | | | 1.65 | | | 0.064 |
| a3 | 0.65 | | 0.85 | 0.025 | | 0.033 |
| b | 0.35 | | 0.48 | 0.013 | | 0.018 |
| b1 | 0.19 | | 0.25 | 0.007 | | 0.010 |
| C | 0.25 | | 0.5 | 0.010 | | 0.019 |
| c1 | | 45 (typ.) | | | | |
| D | 4.8 | | 5.0 | 0.188 | | 0.196 |
| E | 5.8 | | 6.2 | 0.228 | | 0.244 |
| e | | 1.27 | | | 0.050 | |
| e3 | | 3.81 | | | 0.150 | |
| F | 3.8 | | 4.0 | 0.14 | | 0.157 |
| L | 0.4 | | 1.27 | 0.015 | | 0.050 |
| M | | | 0.6 | | | 0.023 |
| S | | 8 (max.) | | | | |



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